

BLE Module

MS88SF2

DateSheet

V 1.1.0

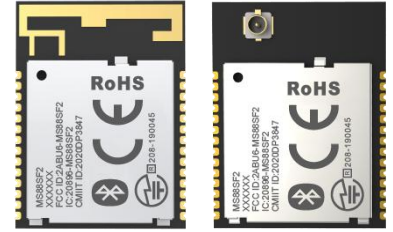
Applicable Product Model
MS88SF2-nRF52833

Version Note

Version	Details	Contributor(s)	Date	Notes
1.0.0	First edit	Eddie	2022.03.01	
1.1.0	Layout Changes	Michelle	2023.10.07	

MS88SF2-nRF52833

High-performance, fully certified, multi-protocol Bluetooth 5.4 module



PCB

IPEX

The MS88SF2 is a low-power, cost-effective wireless BLE 5.4 module based on the nRF52833 SoC. It has an ARM core Cortex-M4F RF transceiver, the core running speed of 64Mhz, in addition, it also comes with 512kB FLASH program space, 128kB RAM, integrated 2.4 GH transceiver, and other powerful supporting resources for Bluetooth connectivity to provide the perfect solution. nRF52833 can support ANT, BLE, BLE MESH, ZIGBEE and THREAD protocols, BLE MESH, ZIGBEE and THREAD protocols. With a data rate of 125kbps, its range in open space is estimated to be up to 250 meters.

■ Features

- Bluetooth 5.4
- Fully certified
- High-performance
- Support ANT, BLE, BLE MESH, ZIGBEE and THREAD protocols, etc

■ Certification Information

BQB、CE、FCC、REACH、ROHS、SRRC、TELEC、IC、WPC、RCM, etc

■ Application

- Smart Buildings
- Consumer Electronics
- Smart Healthcare
- Security Equipment
- Automotive Devices
- Smart Agriculture

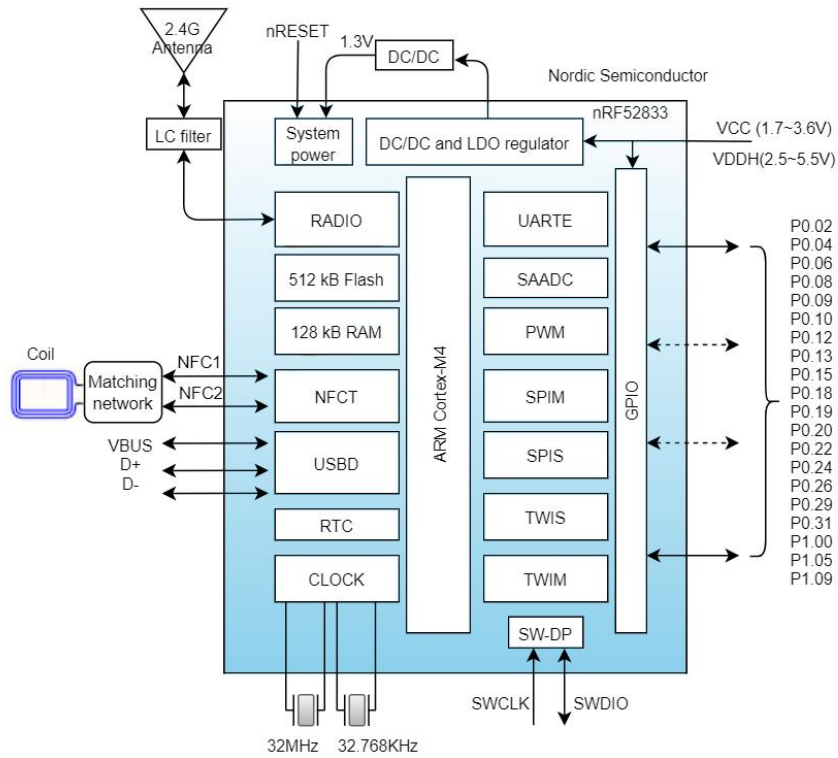
■ Key parameter

Chip Model	nRF52833	Antenna	PCB/IPEX
Module Size	23.2×17.4×2mm	GPIO	20
Flash	512KB	RAM	128KB
Receiving Sensitivity	-96dBm(1Mbps) -103dBm(125kbps)	Transmission Power	-40 ~ +8dBm
Current(TX)	0dBm-4.9mA	Current(RX)	4.6mA

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1 Block Diagram

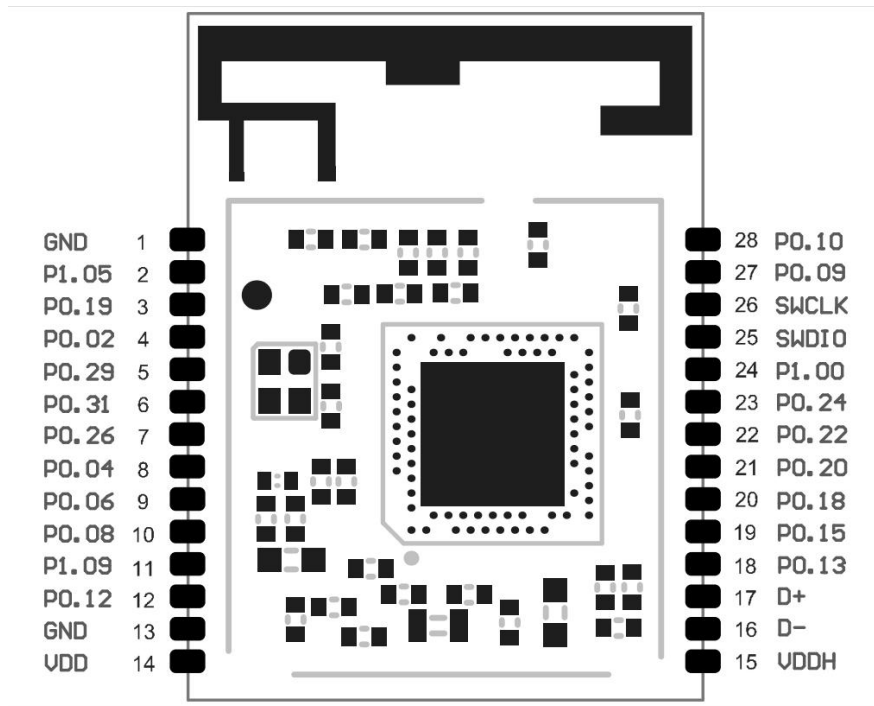


2 Electrical Specification

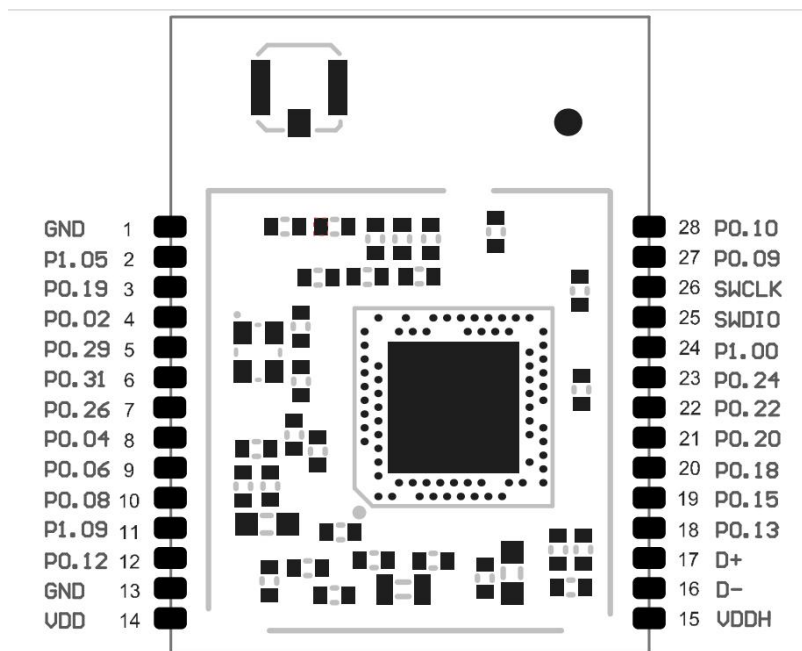
Parameter	Values	Notes
Working Voltage	1.7V-5.5V	To ensure RF work, supply voltage suggest not lower than 2.3V
Working Temperature	-40°C~+85°C	Storage temperature is -40°C~+125°C
Transmission Power	-40 ~ +8dBm	Configurable
Current(RX)	4.6mA	RF receiving current under 1Mbps pattern
Current(TX)	4.8mA	RF transmission current under 0dB pattern
Module Dimension	23.2*17.4*2mm	
Quantity of IO Port	20	

3 Pin Description

3.1 PCB Antenna



3.2 IPEX connector

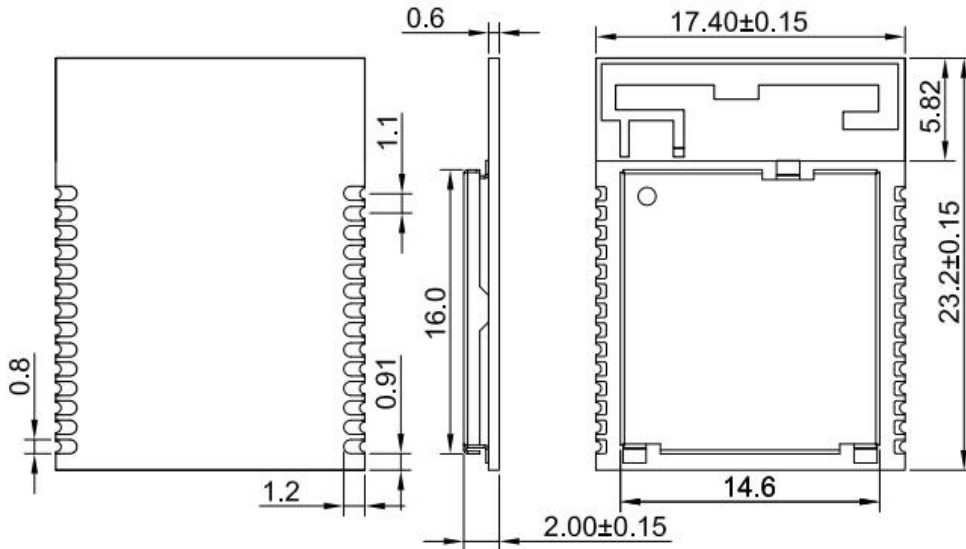


4 Pin Definition

Pin Number	Symbol	Type	Definition
14	VDD	power supply	Power supply, 1.7V-3.6V, use this pin for power supply, need to short VDD and VDDH
15	VDDH	power supply	Power supply, 2.5V-5.5V, use this pin for power supply, not connected to VDD pin
1/13	GND	ground	ground
26/25	SWCLK/SW DIO	Burn Pins	Burn pins, burn only need to connect the power supply pin, ground, and these two pins
2-12/18-24/ 27-28	P0.02-P0.31 P1.00-P1.09	I/O	General Purpose I/O Port
17	D+	Digital interfaces	USB D+
16	D-	Digital interfaces	USB D-

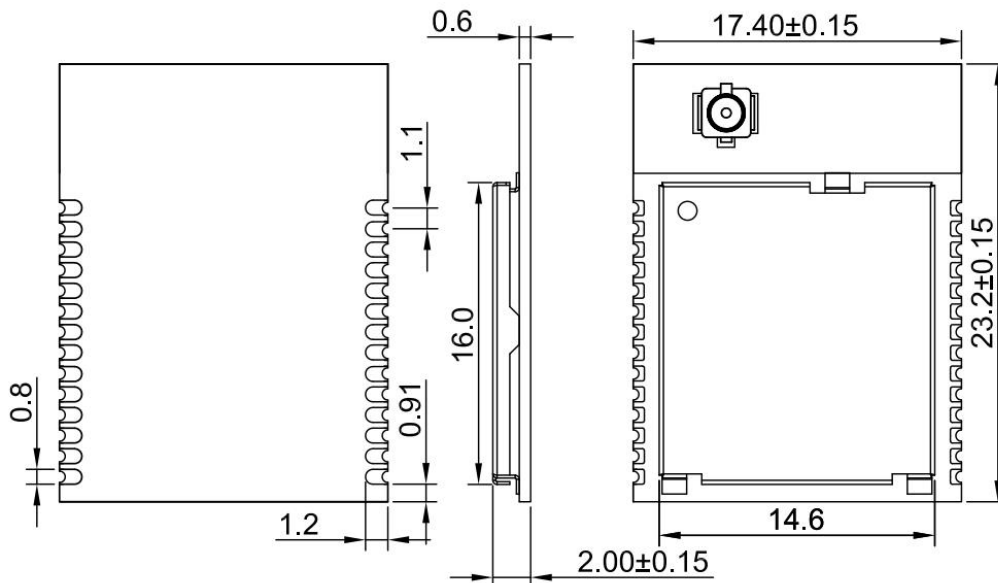
5 Mechanical Drawing

5.1 PCB Antenna



* (Default unit: mm Default tolerance: ±0.1)

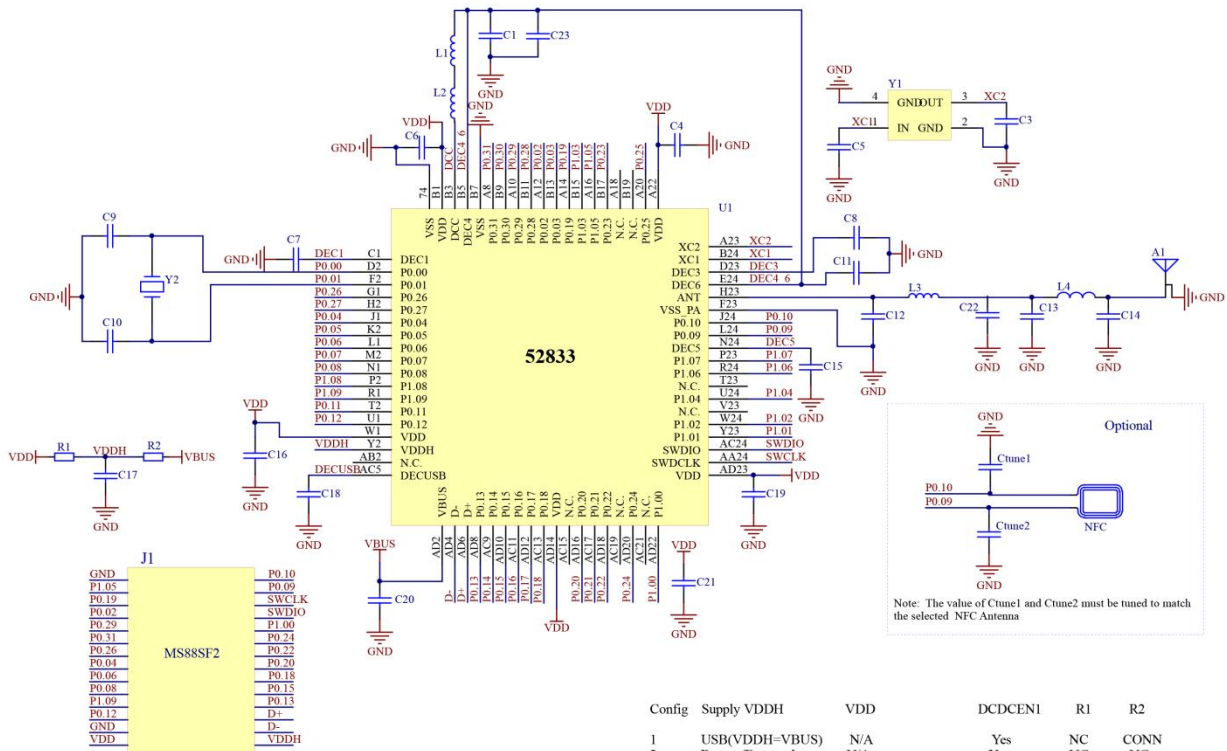
5.2 IPEX connector



* (Default unit: mm Default tolerance: ±0.1)

Notice: The recommended pad size is 1.8*0.8mm with a pad extension of 0.5mm

6 Electrical Schematic



Config Supply VDDH VDD DCDCEN1 R1 R2

1 USB(VDDH=VBUS) N/A Yes NC CONN

2 Battery/Ext.regulator N/A Yes NC NC

3 N/A Battery/Ext.regulator Yes CON NC

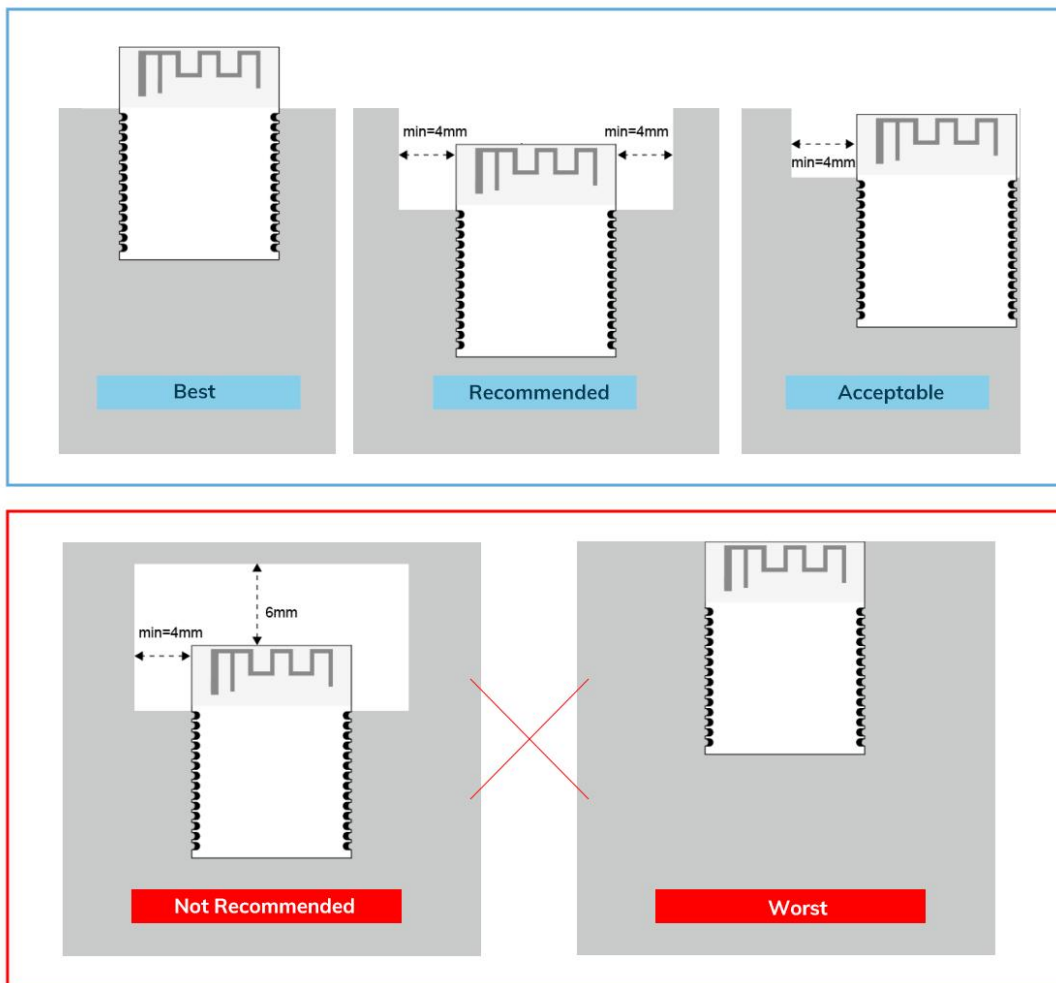
USB can be used in config 1 or 2 for R2 is connected, and highly recommended to solder a 4.7R resistor on the external circuit of VDDH pin in series

Notice: Before placing an order, please confirm the specific configuration required with the salesperson.

7 PCB Layout

Module antenna area couldn't have GND plane or metal cross line, couldn't place components nearby. It is better to make hollow out or clearance treatment or place it on the edge of PCB board.

Notice: Refer to examples as below, and highly suggest to use the first design and the adjustment of modules antenna design according to the first wiring.



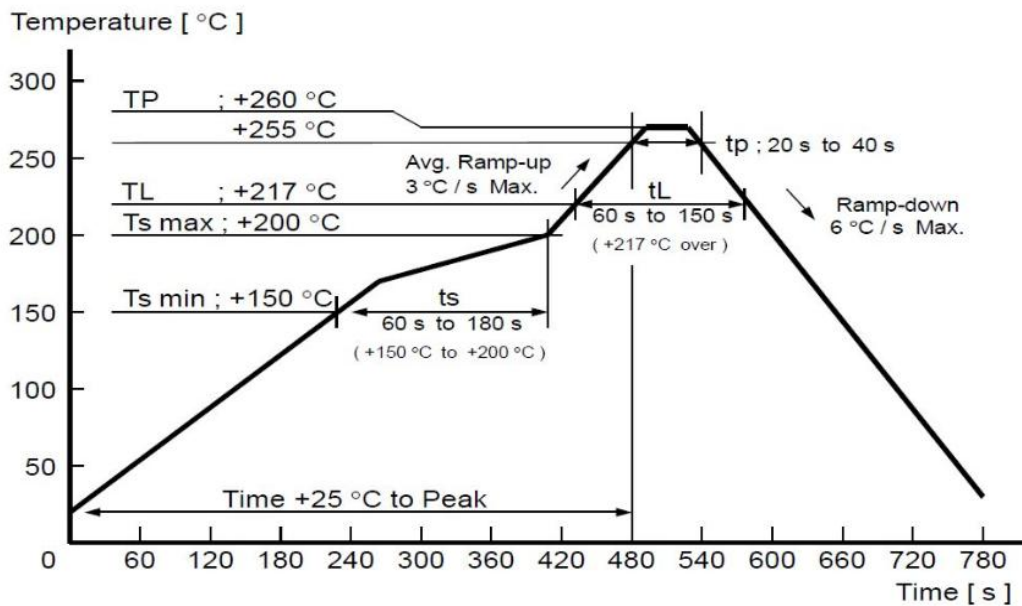
Layout notes:

- 1) Preferred Module antenna area completely clearance and not be prevented by metals, otherwise it will influence antenna's effect (as above DWG. indication).
- 2) Cover the external part of module antenna area with copper as far as possible to reduce the main board's signal cable and other disturbing.
- 3) It is preferred to have a clearance area of 4 square meter or more area around the module antenna (including the shell) to reduce the influence to antenna.
- 4) Device should be grounded well to reduce the parasitic inductance.
- 5) Do not cover copper under module's antenna in order to avoid affect signal radiation or lead to transmission distance affected.
- 6) Antenna should keep far from other circuits to prevent radiation efficiency reduction or affects the normal operation of other lines.
- 7) Module should be placed on edge of circuit board and keep a distance away from other circuits.
- 8) Suggesting to use magnetic beads to insulate module's access power supply.

8 Reflow and Soldering

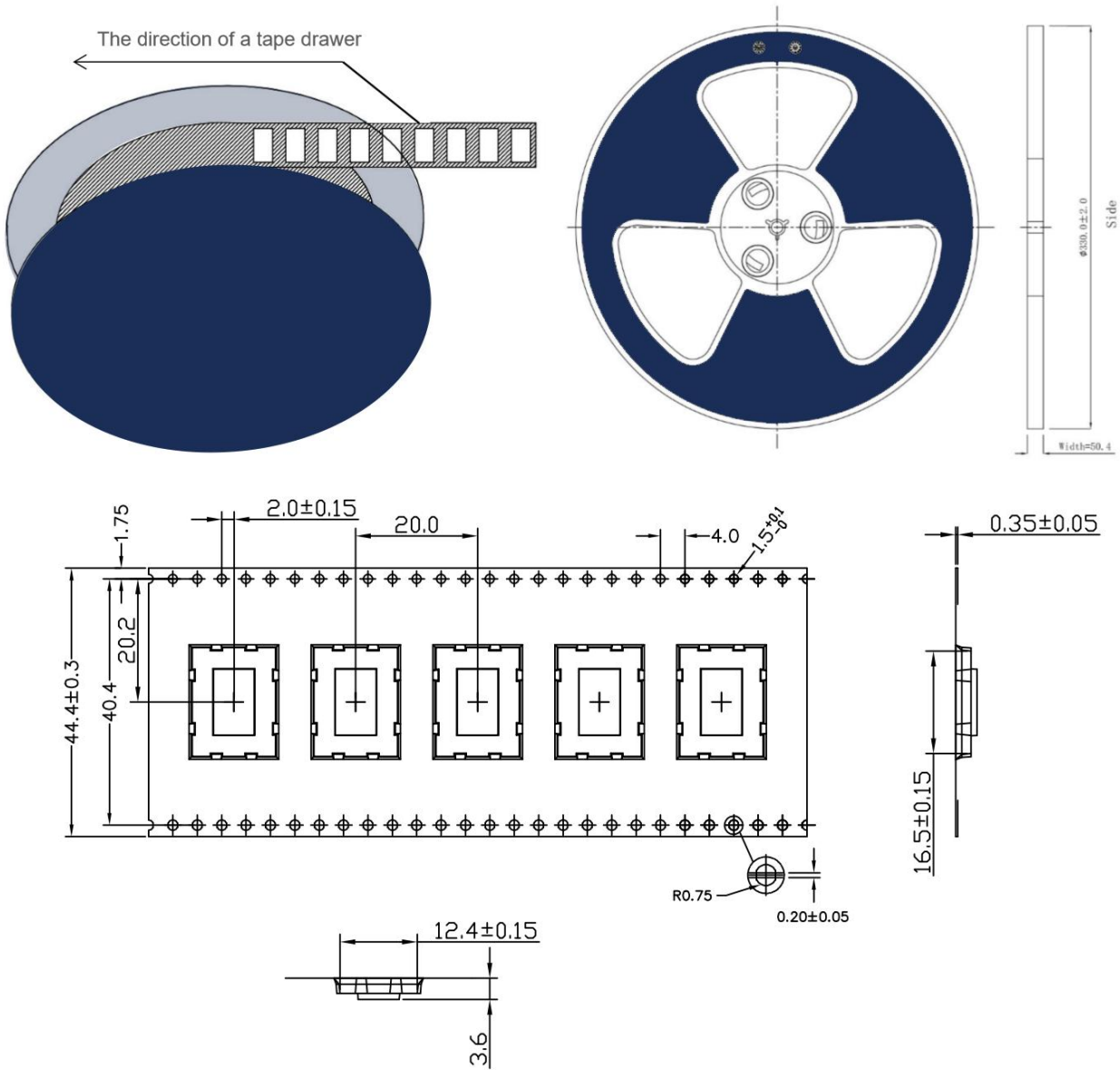
1) Do SMT according to above reflow oven temperature deal curve. Max. Temperature is 260°C;

Refer to IPC/JEDEC standard; Peak TEMP<260°C; Times: ≤2 times, suggest only do once reflow soldering on module surface in case of SMT double pad involved. Contact us if special crafts involved.



- 2) Suggesting to make 0.2mm thickness of module SMT for partial ladder steel mesh, then make the opening extend 0.8mm
- 3) After unsealing, it cannot be used up at one time, should be vacuumed for storage, couldn't be exposed in the air for long time. Please avoid getting damp and soldering-pan oxidizing. If there are 7 to 30 days interval before using online SMT, suggest to bake at 65-70 °C for 24 hours without disassembling the tape.
- 4) Before using SMT, please adopt ESD protection measure.

9 Package Information



* (Default unit: mm Default tolerance: ± 0.1)

Packing detail	Specification	Net weight	Gross weight	Dimension
Quantity	650PCS	689g	1520g	W: 44mm,T:0.35mm

*** Note:** Default weight tolerance all are within 10g (except the special notes)

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● Contact Us

Shenzhen Minewsemi Co., Ltd. is committed to swiftly delivering top-quality connectivity modules to our customers. For assistance and support, please feel free to contact our relevant personnel, or contact us as follows:

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Click the icon to view and download the latest product documents electronically.



Related documents: Chip specification

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